Title (en)

METHOD AND DEVICE FOR CONTROLLING ELECTROCHEMICAL SURFACE PROCESSES

Title (de)

VERFAHREN UND VORRICHTUNG ZUM STEUERN VON ELEKTROCHEMISCHEN OBERFLÄCHENPROZESSEN

Title (fr)

PROCÉDÉ ET DISPOSITIF DE COMMANDE DE TRAITEMENTS ÉLECTROCHIMIQUES DE SURFACES

Publication

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Application

EP 10732271 A 20100518

Priority

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Abstract (en)

[origin: WO2010133222A2] The invention relates to a method and a device for the electrochemical treatment of substrates in continuous installations or dip coating installations including the electric contacting of the material (1) on opposite edges by means of right-hand and left-hand contacts (3', 3''). According to the prior art, the material is treated to a different degree at a right angle to the direction of transport with the minimum being in the region of the center of the material. In order to achieve a completely even electroplating of the material, two electrolytic cells (8, 8'') which are preferably of the same size and have individual anodes (7', 7'') and rectifiers (6, 6'') are arranged at a right angle to the direction of transport as the right-hand and left-hand elements. The right-hand cell (8') is cathodically supplied with electroplating current via the left-hand contact (3'') and the left-hand cell (8'') via the right-hand contact (3'). The treatment of the material (1) can be controlled in a very precise manner, i.e. to give an even result, by differently set currents in the two cells (8', 8'') which currents act on the respective sides alternately in time, i.e. by simply controlling or regulating the current intensity of the rectifier (6', 6'') of the two sides.

IPC 8 full level

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Citation (search report)

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